



Material Content Data Sheet



Sales Product Name		BSO200P03S H		Issued		2. August 2018		
MA#		MA000719884						
Package		PG-DSO-8-39		Weight*		83.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	1.99	1.99	19905	19905
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		123	
	non noble metal	zinc	7440-66-6	0.041	0.05		490	
	non noble metal	iron	7439-89-6	0.820	0.98		9805	
wire	non noble metal	copper	7440-50-8	33.276	39.81	40.85	398139	408557
	non noble metal	copper	7440-50-8	0.139	0.17	0.17	1659	1659
	encapsulation	organic material	carbon black	1333-86-4	0.231	0.28		2763
encapsulation	plastics	epoxy resin	-	7.160	8.57		85666	
	inorganic material	silicondioxide	60676-86-0	38.802	46.42	55.27	464254	552683
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9737	9737
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	868	868
glue	plastics	epoxy resin	-	0.083	0.10		989	
	noble metal	silver	7440-22-4	0.468	0.56	0.66	5602	6591
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com